

Attorney's Docket No: AVAN 2727

DECLARATION FOR PATENT APPLICATION
(COMBINED WITH POWER OF ATTORNEY)
(ORIGINAL APPLICATION)

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name. I believe I am the original, first, and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

CONVOLUTIONAL INTERLEAVER AND DEINTERLEAVER

the specification of which is attached hereto unless box (a) or (b) is checked, in which case

(a) ☐ the specification was filed on _____ as Application No.

(b) ☐ the specification was filed as PCT International Application No. _____ filed on _____ and was amended under PCT Art. 19 on _____ (if any).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56.

I have identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America and filed less than 12 months (6 months for designs) prior to this United States application and of which I claim foreign priority benefits under Title 35, United States Code, Sec. 119, and I have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed.

EARLIEST FOREIGN APPLICATION, AND ALL FOREIGN
APPLICATIONS FILED MORE THAN 12 MONTHS (6 MONTHS FOR DESIGN)
PRIOR TO THIS U.S. APPLICATION

<u>Country</u>	<u>Application No.</u>	<u>Date of Filing</u> (MM/DD/YYYY)
_____	_____	_____

As a named inventor, I hereby appoint the practitioners associated with Customer Number 007812 (John Smith-Hill, Reg. No. 27,730 and Daniel J. Bedell, Reg. No. 30,156) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith and in connection with the resulting patent.

Send correspondence to the correspondence address associated with Customer Number 007812.


I am signing this power of attorney in order that the Patent and Trademark Office will correspond with the practitioners identified in the power of attorney in proceedings before the Patent and Trademark Office, and I do not intend that the power of attorney in itself create an attorney/client or other fiduciary relationship with Smith-Hill and Bedell, P.C. or any of the identified practitioners.

I hereby authorize the practitioners that I have appointed to accept instructions regarding this application and the resulting patent from REALTEK SEMICONDUCTOR CORP.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both under Title 18, United States Code, Sec. 1001, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first joint inventor:

Bin WAN

Inventor's signature 

Date 9/22/2003 Country of Citizenship: People's Republic of China

Residence: Sunnyvale, California

Post Office Address: 1111 Reed Avenue, #D

Sunnyvale, California 94086

Full name of second joint inventor, if any:

Chia-Liang LIN

Inventor's signature 

Date 9/22/2003 Country of Citizenship: Taiwan

Residence: Union City, California

Post Office Address: 33745 Heartland Court

Union City, California 94587

Attorney Docket: AVAN 2727
Postcard: 09/03-29

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECORDATION COVER SHEET

Mail Stop Assignment Recordation Services
Director of the United States Patent and Trademark Office
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please record the attached original document or copy thereof.

Submission Type:

Conveyance Type:

☒ New
☐ Resubmission (Non-Recordation)
Document ID # _____
☐ Correction of PTO Error
Reel # _____; Frame # _____
☐ Corrective Document
Reel # _____; Frame # _____

☒ Assignment
☐ License
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Other _____

Name of conveying party(ies): Bin Wan
Chia-Liang Lin

Execution Date: September 22, 2003

Name and address of receiving party:

REALTEK SEMICONDUCTOR CORP.
No. 2, Industry East Road IX
Science-Based Industrial Park
Hsinchu, Taiwan

Correspondent Name and Address:

Smith-Hill and Bedell, P.C.
12670 N.W. Barnes Road, Suite 104
Portland, Oregon 97229

Tel: (503) 574-3100

Number of Pages: 2

Application Number(s) or Patent Number(s):


☒ Application No. _____ ☐ Patent No: _____
Executed on September 22, 2003

Number of properties affected: 1

A check including the amount of \$40.00 for the fee under 37 CFR 3.41 is enclosed.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.


Penelope Stockwell


Date

09/30/2003 HAFED1 00000038 10669308 40.00 DP 03 FC:8021

Attorney's Docket No. AVAN 2727

A S S I G N M E N T

(To Be Submitted With Application)

WHEREAS, We, Bin Wan and Chia-Liang Lin, residents of Sunnyvale, California and Union City, California, respectively, are joint inventors of an improvement in or relating to CONVOLUTIONAL INTERLEAVER AND DEINTERLEAVER for which we are about to make application for Letters Patent of the United States of America.

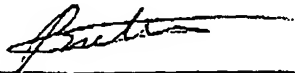
WHEREAS, REALTEK SEMICONDUCTOR CORP. of No. 2, Industry East Road IX, Science-Based Industrial Park, Hsinchu, Taiwan is desirous of acquiring an interest therein.

NOW, THEREFORE, in consideration of One Dollar (\$1) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, Bin Wan and Chia-Liang Lin, assign and transfer to REALTEK SEMICONDUCTOR CORP., our entire legal and equitable right, title, and interest for the territory of the United States of America, and for all foreign countries, in and to the invention described and claimed in the application executed by us on September 22, 2003, preparatory to obtaining Letters Patent of the United States for said invention (and we authorize the attorneys of record to insert the date of execution of the application); said invention, application, and Letters Patent in this or any foreign country, and all divisions, continuations, reissues, and extensions thereof, to be held and enjoyed by the said

REALTEK SEMICONDUCTOR CORP. for its own use and behalf, and for its successors and assigns, to the full end of the term for which Letters Patent may be granted in this or any foreign country, as fully and entirely as the same would have been held by us had this assignment and sale not been made, and we warrant that we have full right to do so, and agree that we shall communicate to the said REALTEK SEMICONDUCTOR CORP., or its successors and assigns any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful declarations, and generally do everything possible to aid REALTEK SEMICONDUCTOR CORP., its successors and assigns, to obtain and enforce proper patent protection for said invention in this or any foreign country.


We agree that no attorney/client or other fiduciary relationship exists between us and Smith-Hill and Bedell, P.C.

EXECUTED at Milpitas, California, this 22th day of September, 2003, by



Bin Wan

EXECUTED at Milpitas, California, this 22nd day of September, 2003, by



Chia-Liang Lin